Single 2-Input AND Gate

The NL17SZ08 is a single 2-input AND Gate in two tiny footprint packages. The device performs much as LCX multi-gate products in speed and drive. They should be used wherever the need for higher speed and drive are needed.

Features

- Tiny SOT-353 and SOT-553 Packages
- 2.7 ns T_{PD} at 5.0 V (typ)
- Source/Sink 24 mA at 3.0 V
- Over-Voltage Tolerant Inputs
- Pin For Pin with NC7SZ08P5X, TC7SZ08FU and TC7SZ08AFE
- Chip Complexity: FETs = 20
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Pb-Free Packages are Available

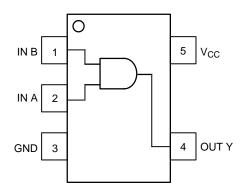


Figure 1. Pinout (Top View)

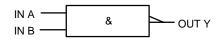


Figure 2. Logic Symbol



ON Semiconductor®

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SOT-353/SC70-5/SC-88A DF SUFFIX CASE 419A

MARKING DIAGRAMS



d = Date Code



SOT-553 XV5 SUFFIX CASE 463B



L2 = Device MarkingD = One Digit Date Code

PIN ASSIGNMENT

Pin	Function
1	In B
2	In A
3	GND
4	Out Y
5	V _{CC}

FUNCTION TABLE

Inp	Input				
Α	В	Y			
L	L	L			
L	Н	L			
Н	L	L			
Н	Н	Н			

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{IN}	DC Input Voltage	-0.5 to +7.0	V	
V _{OUT}	DC Output Voltage		-0.5 to $V_{CC} + 0.5$	V
I _{IK}	DC Input Diode Current		-50	mA
I _{OK}	DC Output Diode Current		-50	mA
I _{OUT}	DC Output Sink Current		±50	mA
I _{CC}	DC Supply Current per Supply Pin	±100	mA	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature Under Bias		+150	°C
$\theta_{\sf JA}$	Thermal Resistance St	OT-353 (Note 1) SOT-553	350 496	°C/W
P _D	Power Dissipation in Still Air at 85°C	SOT-353 SOT-553	186 135	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating Oxyger	Index: 28 to 34	UL 94 V-0 @ 0.125 in	
ESD	Machine	Model (Note 2) Model (Note 3) Model (Note 4)	Class Z Class A N/A	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- 2. Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.
- 3. Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V _{CC}	DC Supply Voltage		1.65	5.5	V
V _{IN}	DC Input Voltage		0	5.5	V
V _{OUT}	DC Output Voltage		0	V _{CC} + 0.5	V
T _A	Operating Temperature Range		-40	+85	°C
t _r , t _f	Input Rise and Fall Time $ V_{CC} = 3.0 \text{ V} \pm 0.0 $ $ V_{CC} = 5.0 \text{ V} \pm 0.0 $	0.3 V 0.5 V	0 0	100 20	ns/V

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	T	A = 25°	С	$-40^{\circ}\text{C} \leq \text{T}_{\text{A}} \leq 85^{\circ}\text{C}$		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 V _{CC} 0.3 V _{CC}	V
Vон	High-Level Output Voltage V _{IN} = V _{IL} or V _{IH}	I_{OH} = 100 μ A I_{OH} = -3 mA I_{OH} = -8 mA I_{OH} = -12 mA I_{OH} = -16 mA I_{OH} = -24 mA I_{OH} = -32 mA	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V _{CC} 1.52 2.1 2.4 2.7 2.5 4.0		V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8		V
V _{OL}	Low-Level Output Voltage V _{IN} = V _{IH} or V _{OH}	$I_{OL} = 100 \mu A$ $I_{OL} = 3 \text{ mA}$ $I_{OL} = 8 \text{ mA}$ $I_{OL} = 12 \text{ mA}$ $I_{OL} = 16 \text{ mA}$ $I_{OL} = 24 \text{ mA}$ $I_{OL} = 32 \text{ mA}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.20 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I _{IN}	Input Leakage Current	$V_{IN} = V_{CC}$ or GND	0 to 5.5			± 0.1		±1.0	μΑ
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1		10	μΑ

AC ELECTRICAL CHARACTERISTICS $t_R = t_F = 3.0 \text{ ns}$

			V _{CC}		T _A = 25°C		-40°C ≤		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
t _{PLH}	Propagation Delay	$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	1.65	2.0	6.3	12	2.0	12.7	ns
t _{PHL}	(Figure 3 and 4)	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	1.8	2.0	6.2	10	2.0	10.5	
		$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	2.5 ± 0.2	0.8	3.4	7.0	0.8	7.5	
		$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	3.3 ± 0.3	0.5	2.6	4.7	0.5	5.0	
		$R_L = 500 \Omega, C_L = 50 pF$		1.5	3.3	5.2	1.5	5.5	
		$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	5.0 ± 0.5	0.5	2.2	4.1	0.5	4.4	
		$R_L = 500 \Omega, C_L = 50 pF$		0.8	2.7	4.5	0.8	4.8	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	$V_{CC} = 5.5 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	>4.0	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	25	pF
	(Note 5)	10 MHz, V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	30	

^{5.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC} \cdot C_{PD}$ is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

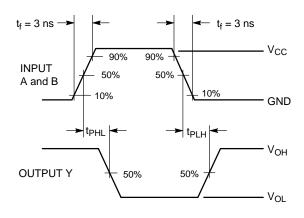
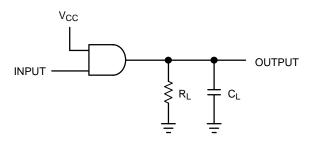


Figure 3. Switching Waveform



A 1–MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

DEVICE ORDERING INFORMATION

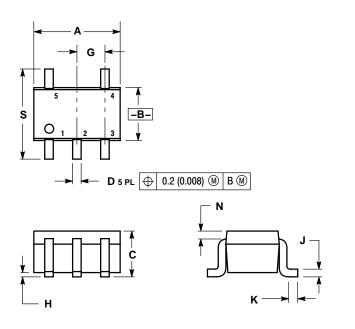
	Device Nomenclature								
Device Order Number	Logic Circuit Indicator	No. of Gates per Package	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape and Reel Suffix	Package Type	Tape and Reel Size [†]
NL17SZ08DFT2	NL	1	7	SZ	08	DF	T2	SC70-5/ SC-88A/ SOT-353	178 mm, 3000 Unit
NL17SZ08DFT2G	NL	1	7	SZ	08	DF	T2	SC70-5/ SC-88A/ SOT-353 (Pb-Free)	178 mm, 3000 Unit
NL17SZ08XV5T2	NL	1	7	SZ	08	XV5	T2	SOT-553*	178 mm 4000 Units

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}All Devices in Package SOT553 are Inherently Pb-Free.

PACKAGE DIMENSIONS

SOT-353 **DF SUFFIX** 5-LEAD PACKAGE CASE 419A-02 ISSUE G



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

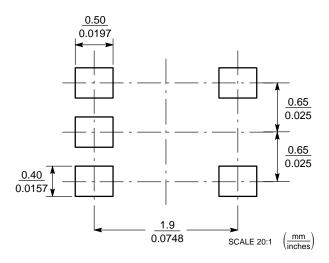
 2. CONTROLLING DIMENSION: INCH.

 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.

 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
С	0.031	0.043	0.80	1.10	
D	0.004	0.012	0.10	0.30	
G	0.026	BSC	0.65 BSC		
Н		0.004		0.10	
J	0.004	0.010	0.10	0.25	
K	0.004	0.012	0.10	0.30	
N	0.008 REF		0.20	REF	
S	0.079	0.087	2.00	2.20	

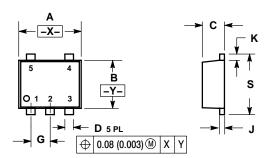
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOT-553 XV5 SUFFIX 5-LEAD PACKAGE CASE 463B-01 **ISSUE A**



- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS

	MILLIN	IETERS	INC	HES
DIM	MIN MAX		MIN	MAX
Α	1.50	1.70	0.059	0.067
В	1.10	1.30	0.043	0.051
С	0.50	0.60	0.020	0.024
D	0.17	0.27	0.007	0.011
G	0.50	BSC	0.020	BSC
J	0.08	0.18	0.003	0.007
K	0.10	0.30	0.004	0.012
9	1 50	1 70	0.050	0.067

PIN 1. BASE 1 EMITTER 1/2 3 BASE 2

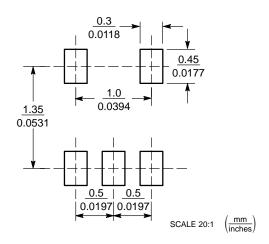
OF BASE MATERIAL

COLLECTOR 2 5. COLLECTOR 1

STYLE 2: PIN 1. CATHODE

2. ANODE 3. CATHODE CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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